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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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#### **DATA SHEET**



# MOS FIELD EFFECT TRANSISTOR NP80N04NUG, NP80N04PUG

## SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The NP80N04NUG and NP80N04PUG are N-channel MOS Field Effect Transistors designed for high current switching applications.

#### **ORDERING INFORMATION**

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
NP80N04NUG-S18-AY Note		Tube 50 p/tube	TO-262 (MP-25SK) typ. 1.8 g
NP80N04PUG-E1B-AY Note	Pure Sn (Tin)	Tape	
NP80N04PUG-E2B-AY Note		1000 p/reel	TO-263 (MP-25ZP) typ. 1.5 g

Note Pb-free (This product does not contain Pb in the external electrode.)

FEATURES (TO-262)

- Non logic level
- Super low on-state resistance
  - NP80N04NUG

 $R_{DS(on)}$  = 4.8 m $\Omega$  MAX. (Vgs = 10 V, ID = 40 A)

- NP80N04PUG

 $R_{DS(on)}$  = 4.5 m $\Omega$  MAX. (VGS = 10 V, ID = 40 A)

High current rating

 $I_{D(DC)} = \pm 80 A$ 

• Low input capacitance

Ciss = 4900 pF TYP.

• Designed for automotive application and AEC-Q101 qualified



(TO-263)



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#### ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Drain to Source Voltage (V <sub>GS</sub> = 0 V)	VDSS	40	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I <sub>D(DC)</sub>	±80	Α
Drain Current (pulse) Note1	ID(pulse)	±300	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	115	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.8	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Repetitive Avalanche Current Note2	IAR	37	Α
Repetitive Avalanche Energy Note2	Ear	137	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

**2.** Tch  $\leq$  150°C, Rg = 25  $\Omega$ 

#### THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	1.30	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W



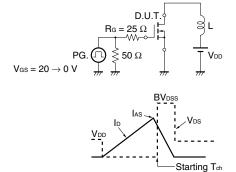
#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

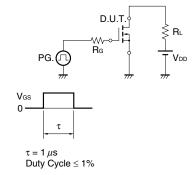
CHARACTERISTICS	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V				1	μΑ
Gate Leakage Current	Igss	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V				±100	nA
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2.0		4.0	٧
Forward Transfer Admittance Note	yfs	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 35 A		25	50		S
Drain to Source On-state Resistance Note	RDS(on)	V <sub>GS</sub> = 10 V,	NP80N04NUG		3.6	4.8	mΩ
		I <sub>D</sub> = 40 A	NP80N04PUG		3.2	4.5	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V,			4900	7350	pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V,			480	720	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz			310	560	pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 40 A,			32	70	ns
Rise Time	tr	V <sub>GS</sub> = 10 V,			23	58	ns
Turn-off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> = 0 Ω			65	130	ns
Fall Time	tf	1			11	28	ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 32 V,			90	135	nC
Gate to Source Charge	Qgs	V <sub>GS</sub> = 10 V,			21		nC
Gate to Drain Charge	Q <sub>GD</sub>	Ip = 80 A			31		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 80 A, V <sub>GS</sub> = 0 V			0.92	1.5	V
Reverse Recovery Time	trr	I <sub>F</sub> = 80 A, V <sub>GS</sub> = 0 V,			40		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ <i>μ</i> s			44		nC

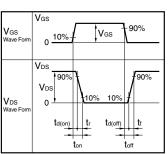
Note Pulsed test

#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

#### TEST CIRCUIT 2 SWITCHING TIME



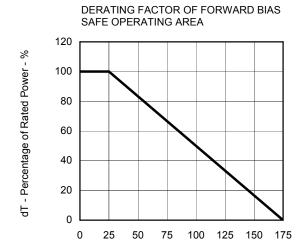




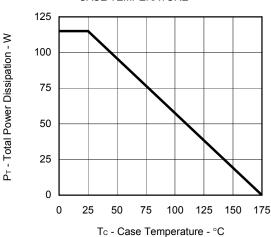
#### **TEST CIRCUIT 3 GATE CHARGE**

$$\begin{array}{c|c} D.U.T. \\ I_G = 2 \text{ mA} \\ \hline \hline W. \\ O. \\ \hline \end{array} \begin{array}{c} PG. \\ \hline \end{array} \begin{array}{c} S & S \\ \hline \end{array} \begin{array}{c} S \\ S & O \\ \hline \end{array} \begin{array}{c} V_{DD} \\ \hline \end{array}$$

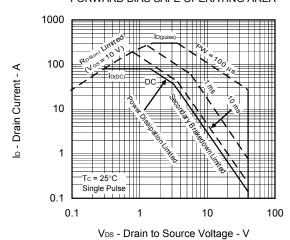
#### TYPICAL CHARACTERISTICS (TA = 25°C)



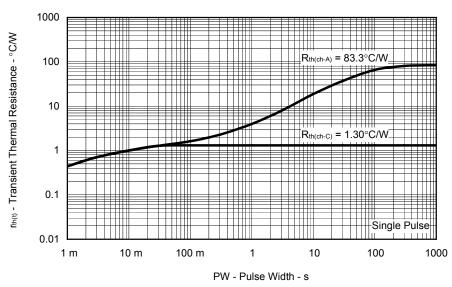
## TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

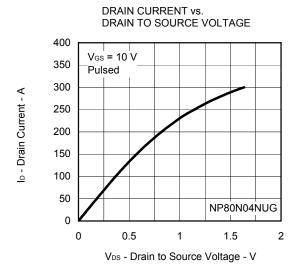


## To - Case Temperature - °C FORWARD BIAS SAFE OPERATING AREA

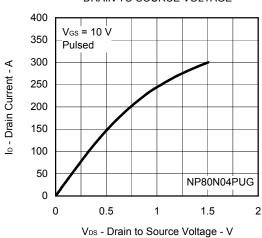


#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

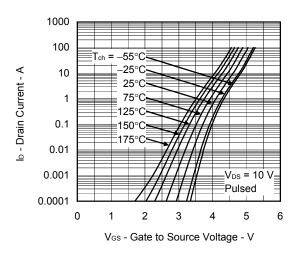




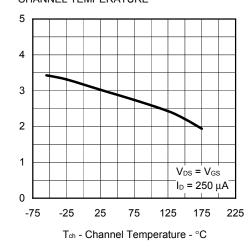
#### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



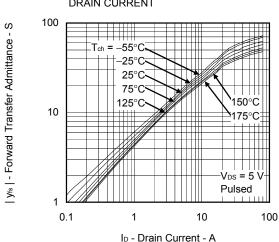
FORWARD TRANSFER CHARACTERISTICS



GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE

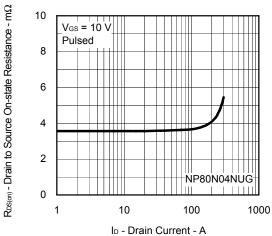


FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

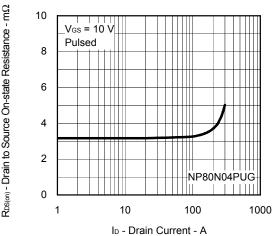


Vos(th) - Gate to Source Threshold Voltage - V

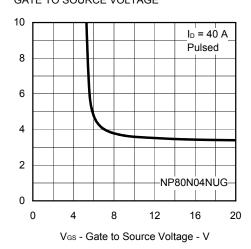
### DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



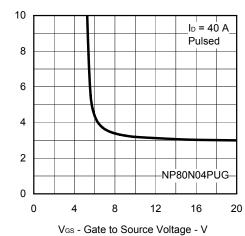
## DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



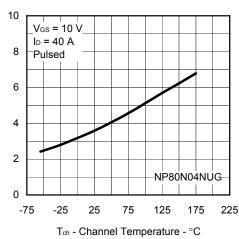
## DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



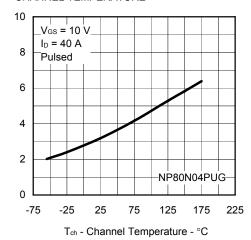
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



## DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



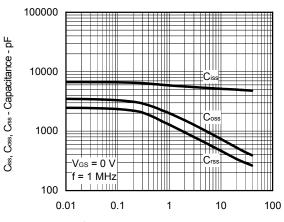
R<sub>DS(m)</sub> - Drain to Source On-state Resistance - mΩ

R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

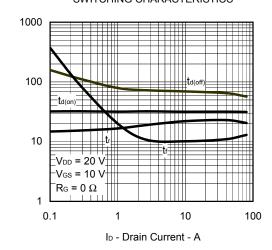
 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

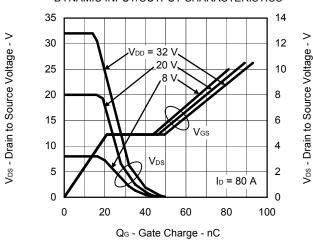


V<sub>DS</sub> - Drain to Source Voltage - V

#### SWITCHING CHARACTERISTICS



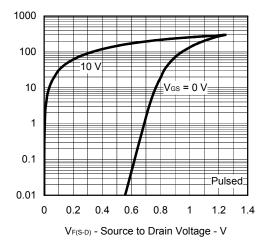
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



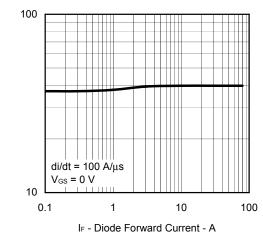
IF - Diode Forward Current - A

.d(on), tr, td(off), tr - Switching Time - ns

SOURCE TO DRAIN DIODE FORWARD VOLTAGE

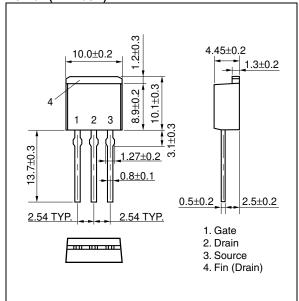


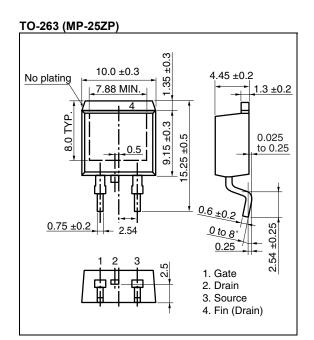
REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



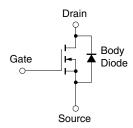
#### PACKAGE DRAWINGS (Unit: mm)







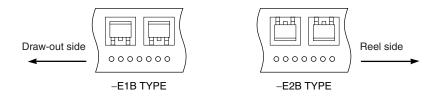
#### **EQUIVALENT CIRCUIT**



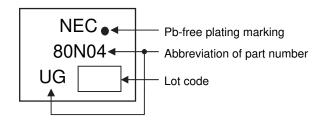
**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

#### **TAPE INFORMATION (NP80N04PUG)**

There are two types (-E1B, -E2B) of taping depending on the direction of the device.



#### MARKING INFORMATION



#### RECOMMENDED SOLDERING CONDITIONS

These products should be soldered and mounted under the following recommended conditions.

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For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Soldering Method	Soldering Conditions	Recommended Condition Symbol	
Infrared reflow NP80N04PUG	Maximum temperature (Package's surface temperature): 260°C or below Time at maximum temperature: 10 seconds or less Time of temperature higher than 220°C: 60 seconds or less Preheating time at 160 to 180°C: 60 to 120 seconds Maximum number of reflow processes: 3 times Maximum chlorine content of rosin flux (percentage mass): 0.2% or less	IR60-00-3	
Wave soldering NP80N04NUG	Maximum temperature (Solder temperature): 260°C or below Time: 10 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	THDWS	
Partial heating NP80N04NUG, NP80N04PUG	Maximum temperature (Pin temperature): 350°C or below Time (per side of the device): 3 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	P350	

Caution Do not use different soldering methods together (except for partial heating).

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